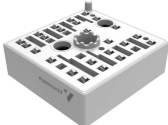
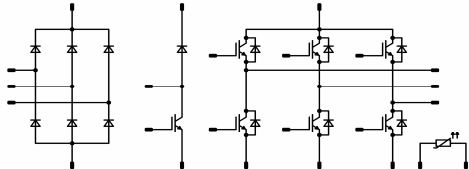




Vincotech

MiniSKiiP® 1 PIM		600 V / 20 A	
Features - Solderless interconnection - Trench Fieldstop IGBT3 technology		MiniSKiiP® 1 housing 	
Target Applications Industrial drives		Schematic 	
Types V23990-K204-A-PM			

Maximum Ratings

$T_J = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}		25	A
Surge (non-repetitive) forward current	I_{FSM}	$t_p = 10\text{ ms}$ half sine wave	220	A
I^2t -value	I^2t		240	A ² s
Power dissipation	P_{tot}	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	46	W
Maximum Junction Temperature	T_{Jmax}		150	°C
Inverter Switch / Brake Switch				
Collector-emitter breakdown voltage	V_{CE}		600	V
DC collector current	I_C		20	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{Jmax}	60	A
Power dissipation	P_{tot}	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	59	W
Gate-emitter peak voltage	V_{GE}		±20	V
Short circuit ratings	t_{SC}	$T_J \leq 150\text{ °C}$ $V_{GE} = 15\text{ V}$ $V_{CC} = 360\text{ V}$	6	µs
Maximum Junction Temperature	T_{Jmax}		175	°C

**Maximum Ratings** $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode / Brake Diode				
Repetitive peak reverse voltage	V_{RRM}		600	V
DC forward current	I_F		20	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	40	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	38	W
Maximum Junction Temperature	T_{jmax}		175	°C

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{is}	$t = 2\text{ s}$ DC Test Voltage*	5500	V
		$t = 1\text{ min}$ AC Voltage	2500	V
Creepage distance		With std lid For more informations see handling instructions	6,3	mm
Clearance		With std lid For more informations see handling instructions	6,3	mm
Comparative Tracking Index	CTI		>200	

* 100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_F [V] V_{CE} [V] V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	Max	
Rectifier Diode										
Forward voltage	V_F				25	25 125		1,51 1,42		V
Threshold voltage (for power loss calc. only)	V_{to}				25	25 125		0,86 0,79		V
Slope resistance (for power loss calc. only)	r_t				25	25 125		0,03 0,03		Ω
Reverse current	I_r			1500		25			0,05	mA
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5$ W/mK (HPTP)						1,37		K/W
Inverter Switch / Brake Switch										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00029	25	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 150	1,1	1,87 2,04	1,9	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	600		25			1,1	μA
Gate-emitter leakage current	I_{GES}		20	0		25			300	nA
Integrated Gate resistor	R_{gint}					25		none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 8\ \Omega$ $R_{gon} = 16\ \Omega$	0/15	300	20	25 150		28 26		ns
Rise time	t_r					25 150		30 35		
Turn-off delay time	$t_{d(off)}$					25 150		225 245		
Fall time	t_f					25 150		79 117		
Turn-on energy loss	E_{on}					25 150		0,72 0,86		mWs
Turn-off energy loss	E_{off}					25 150		0,46 0,59		
Input capacitance	C_{ies}	$f = 1\text{ MHz}$	0	25	25			1100		pF
Output capacitance	C_{oss}							71		
Reverse transfer capacitance	C_{rss}							32		
Gate charge	Q_G		15	480	20	25		123		nC
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5$ W/mK (HPTP)						1,53		K/W
Inverter Diode / Brake Diode										
Diode forward voltage	V_F				20	25 125		1,84 1,85	1,6	V
Peak reverse recovery current	I_{RRM}	$di_{rr}/dt = t_{bd}\text{ A/us}$	0/15	300	20	25 125		9,97 11,88		A
Reverse recovery time	t_{rr}					25 125		259 358		ns
Reverse recovered charge	Q_{rr}					25 125		1,02 1,66		μC
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125		225 64		A/μs
Reverse recovered energy	E_{rec}					25 125		0,18 0,31		mWs
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5$ W/mK (HPTP)						2,13		K/W
Thersmitor										
Rated resistance	R					25		1000		Ω
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1670\ \Omega$				100	-3		3	%
R_{100}	R					100		1670,3125		Ω
A-value	$B_{(25/50)}$					25		$7,635 \cdot 10^{-3}$		1/K
B-value	$B_{(25/100)}$					25		$1,731 \cdot 10^{-5}$		1/K²
Vincotech NTC Reference									E	



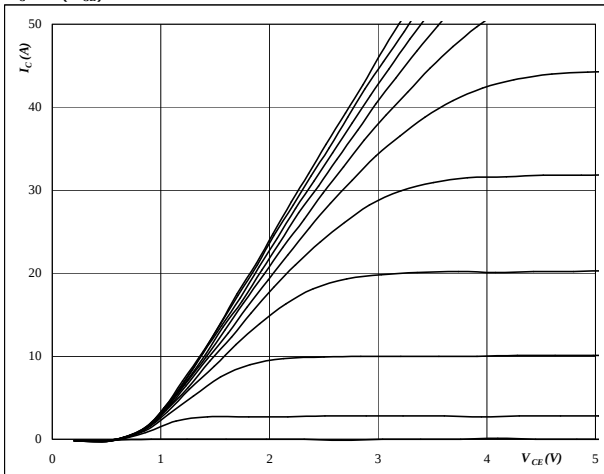
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



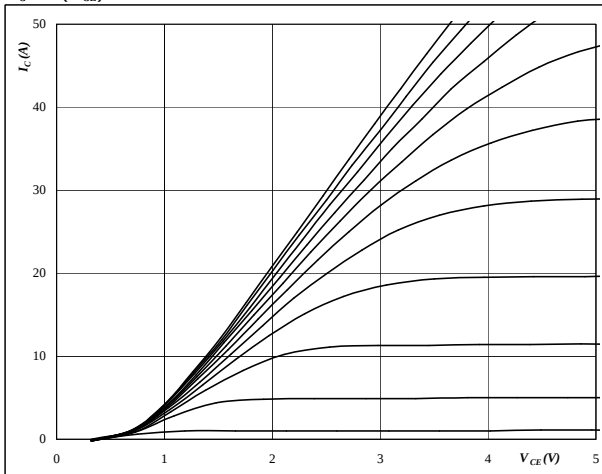
At

$t_p = 250 \mu s$
 $T_j = 25 ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



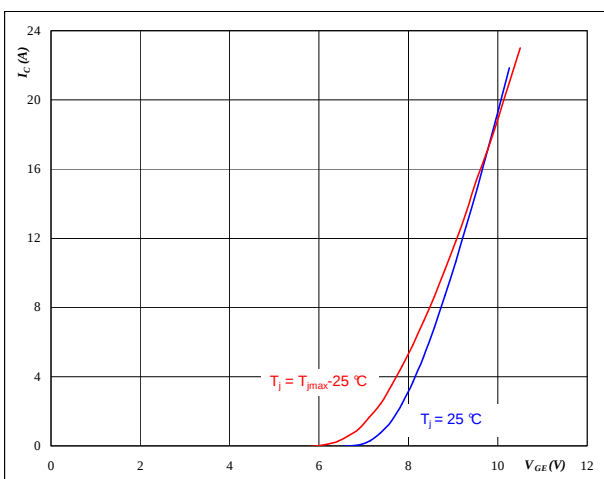
At

$t_p = 250 \mu s$
 $T_j = 125 ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$



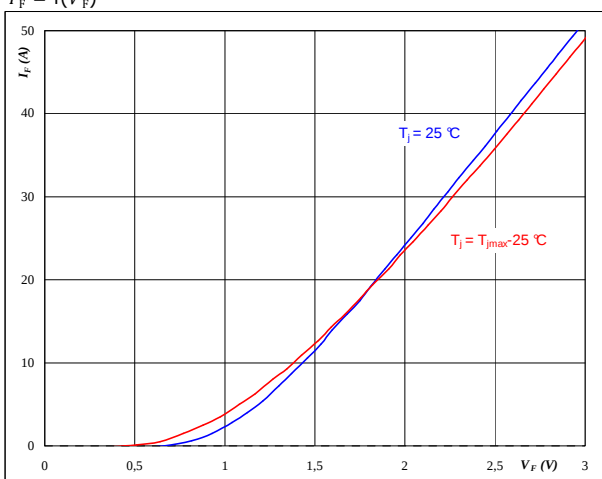
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

figure 4. FWD

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



At

$t_p = 250 \mu s$



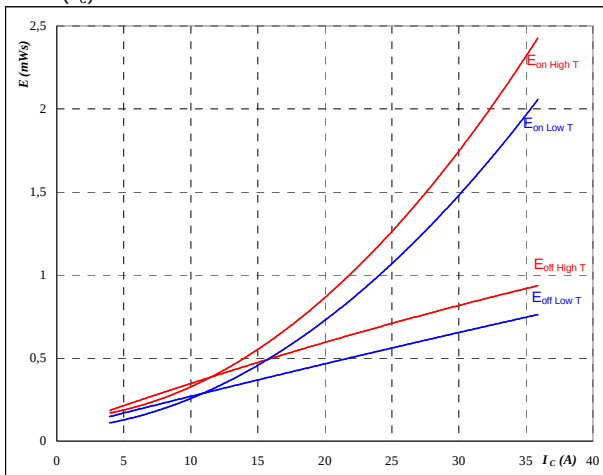
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 5. IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

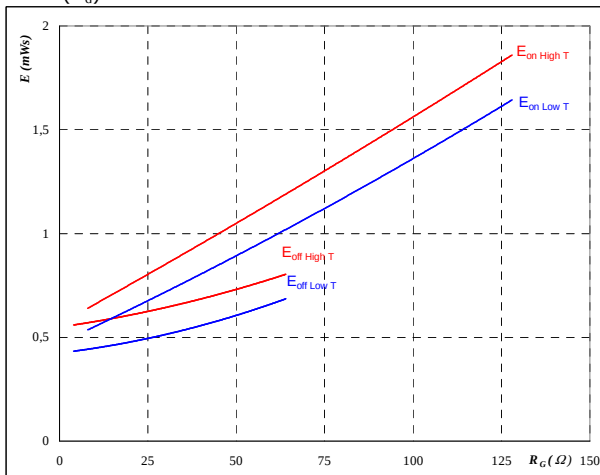
$$R_{gon} = 32 \text{ } \Omega$$

$$R_{goff} = 16 \text{ } \Omega$$

figure 6. IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

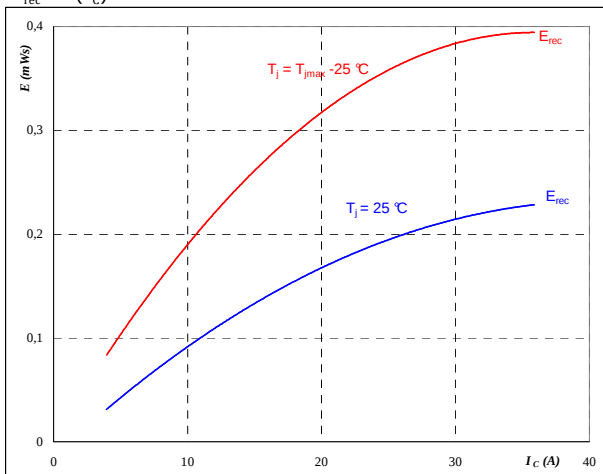
$$V_{GE} = 15 \text{ V}$$

$$I_C = 20 \text{ A}$$

figure 7. FWD

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

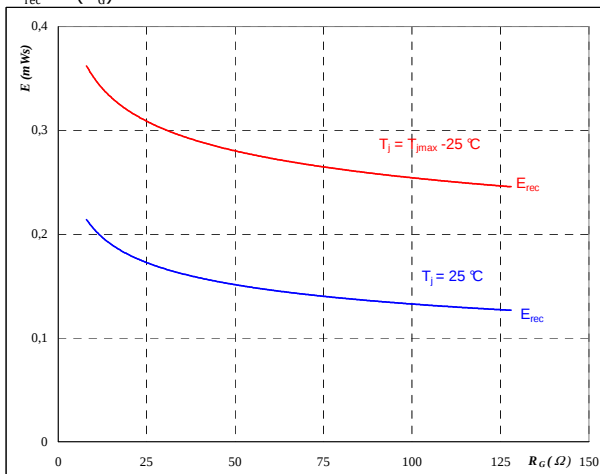
$$V_{GE} = 15 \text{ V}$$

$$R_{gon} = 32 \text{ } \Omega$$

figure 8. FWD

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

$$I_C = 20 \text{ A}$$



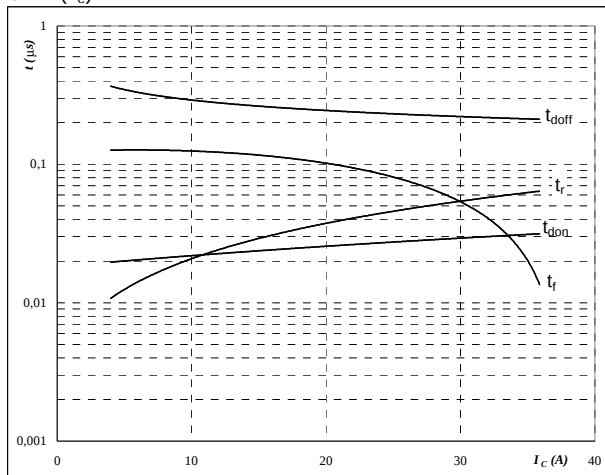
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 9. IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



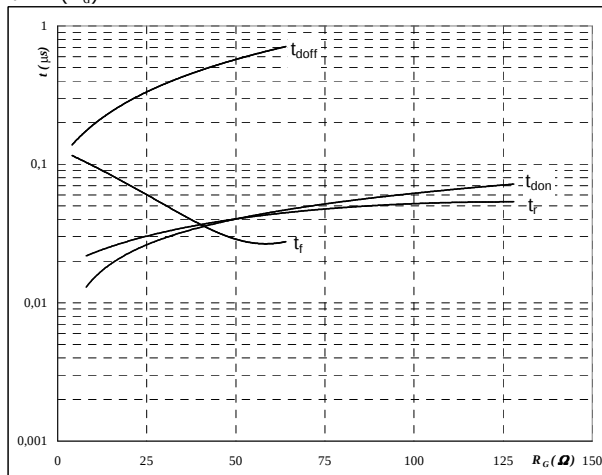
With an inductive load at

$T_j =$	125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$R_{gon} =$	32	Ω
$R_{goff} =$	16	Ω

figure 10. IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



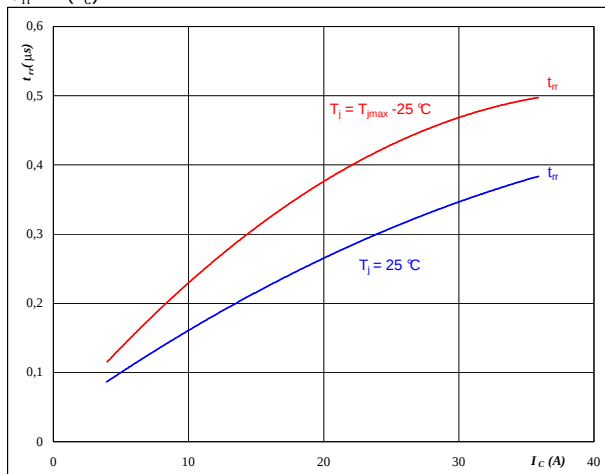
With an inductive load at

$T_j =$	125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$I_C =$	20	A

figure 11. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



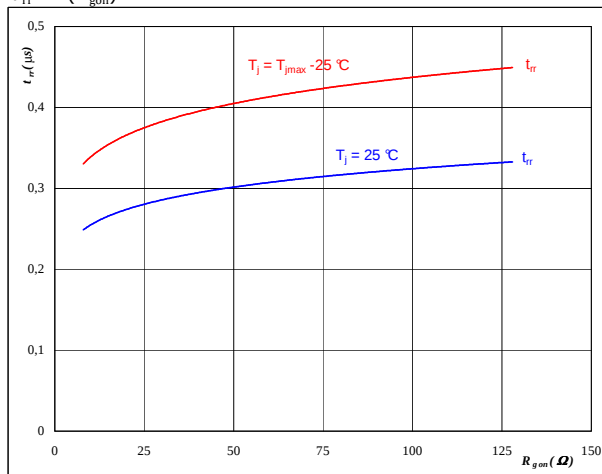
At

$T_j =$	25/125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$R_{gon} =$	32	Ω

figure 12. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

$T_j =$	25/125	°C
$V_R =$	300	V
$I_F =$	20	A
$V_{GE} =$	15	V



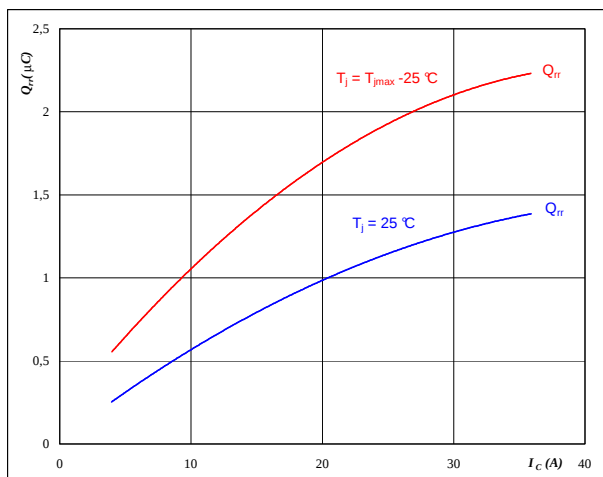
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 13. FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$



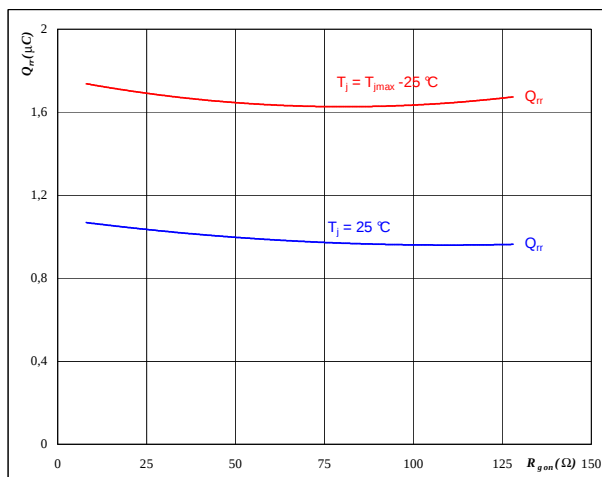
At

$T_j = 25/125\text{ °C}$
 $V_{CE} = 300\text{ V}$
 $V_{GE} = 15\text{ V}$
 $R_{gon} = 32\text{ Ω}$

figure 14. FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



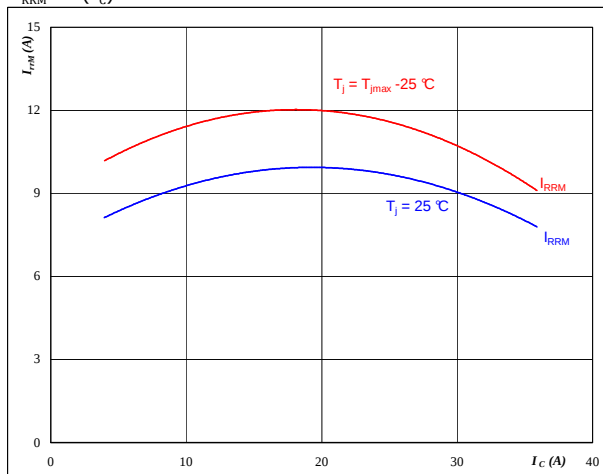
At

$T_j = 25/125\text{ °C}$
 $V_R = 300\text{ V}$
 $I_F = 20\text{ A}$
 $V_{GE} = 15\text{ V}$

figure 15. FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$



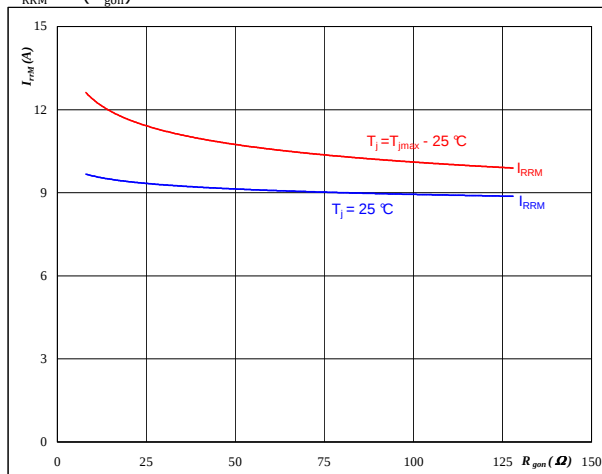
At

$T_j = 25/125\text{ °C}$
 $V_{CE} = 300\text{ V}$
 $V_{GE} = 15\text{ V}$
 $R_{gon} = 32\text{ Ω}$

figure 16. FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



At

$T_j = 25/125\text{ °C}$
 $V_R = 300\text{ V}$
 $I_F = 20\text{ A}$
 $V_{GE} = 15\text{ V}$



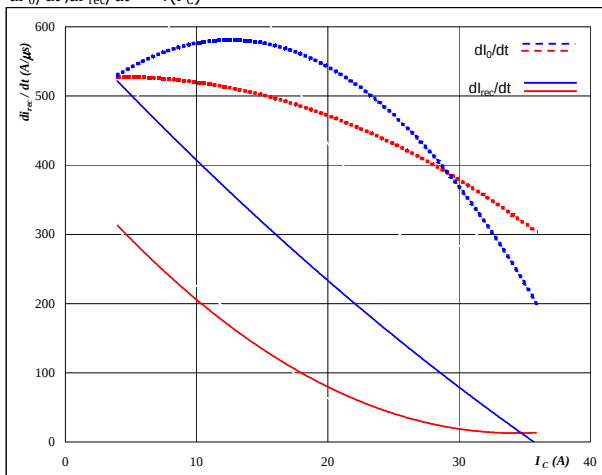
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 17. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$dI_0/dt, dI_{rec}/dt = f(I_C)$$



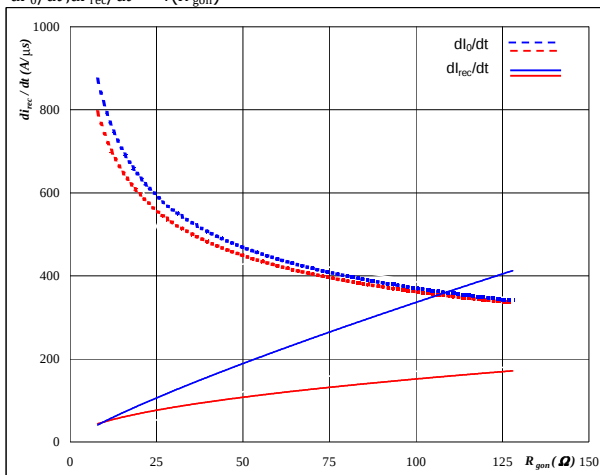
At

$T_j = 25/125$ °C
 $V_{CE} = 300$ V
 $V_{GE} = 15$ V
 $R_{gon} = 32$ Ω

figure 18. FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$dI_0/dt, dI_{rec}/dt = f(R_{gon})$$



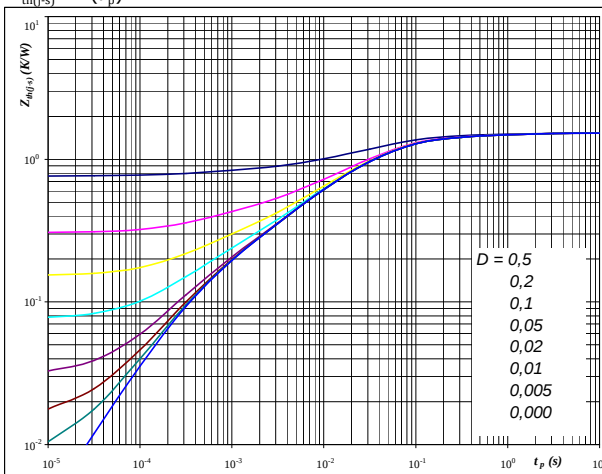
At

$T_j = 25/125$ °C
 $V_R = 300$ V
 $I_F = 20$ A
 $V_{GE} = 15$ V

figure 19. IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$D = t_p / T$
 $R_{th(j-s)} = 1,53$ K/W

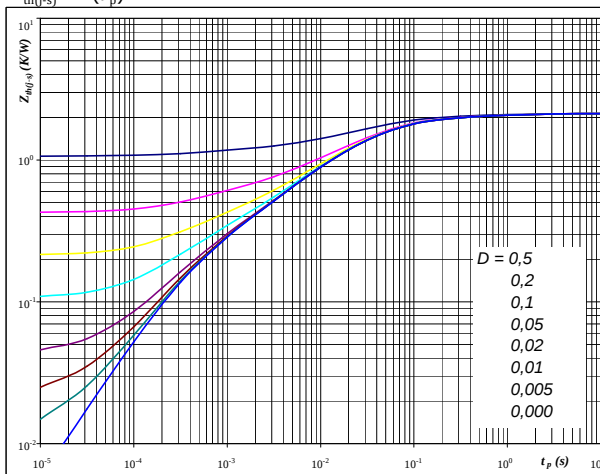
IGBT thermal model values

R (K/W)	Tau (s)
7,52E-02	1,42E+00
1,49E-01	2,20E-01
7,06E-01	4,01E-02
3,62E-01	8,98E-03
1,38E-01	1,93E-03
9,71E-02	3,25E-04

figure 20. FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$D = t_p / T$
 $R_{th(j-s)} = 2,13$ K/W

FWD thermal model values

R (K/W)	Tau (s)
1,19E-01	2,09E+00
2,02E-01	3,18E-01
8,81E-01	6,20E-02
5,30E-01	1,64E-02
2,37E-01	3,98E-03
1,60E-01	5,45E-04



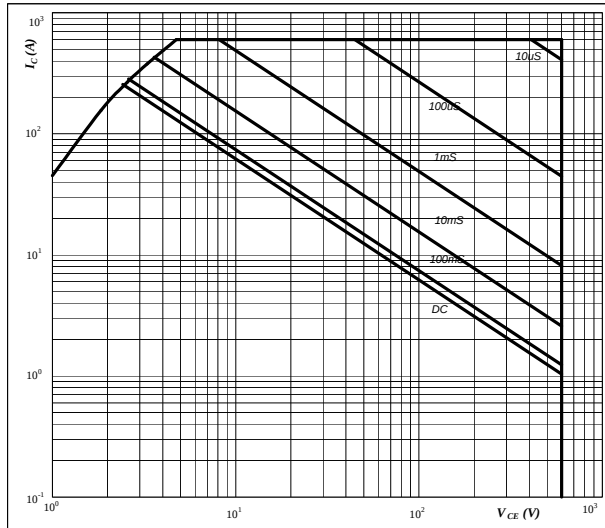
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 25. IGBT

Safe operating area as a function
of collector-emitter voltage

$$I_C = f(V_{CE})$$



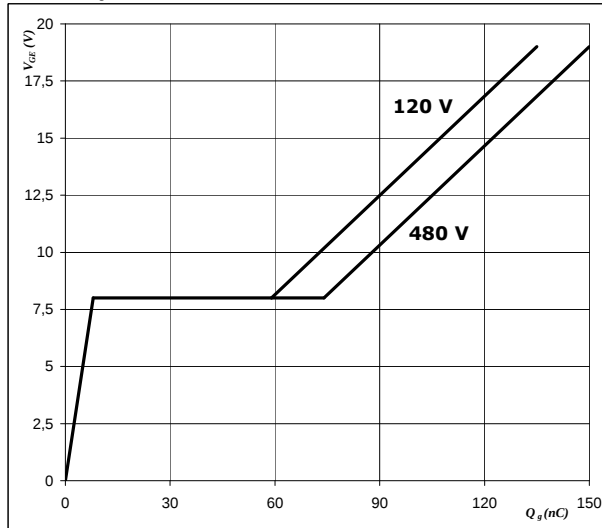
At

$D =$ single pulse
 $T_s =$ 80 °C
 $V_{GE} =$ 15 V
 $T_j = T_{jmax}$

figure 26. IGBT

Gate voltage vs Gate charge

$$V_{GE} = f(Q_g)$$



At

$I_C =$ 20 A

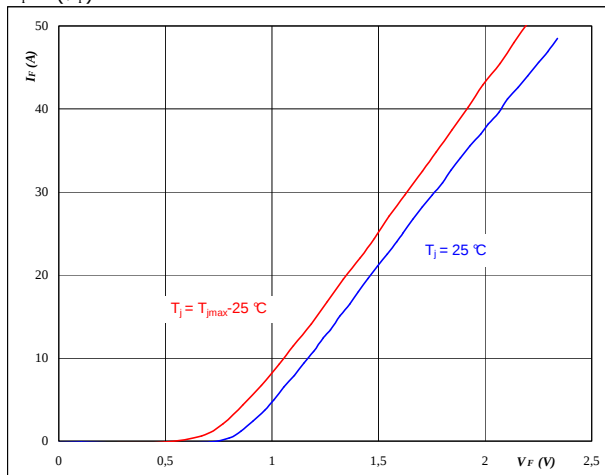


Rectifier Diode

figure 1. Rectifier Diode

Typical diode forward current as
a function of forward voltage

$$I_F = f(V_F)$$



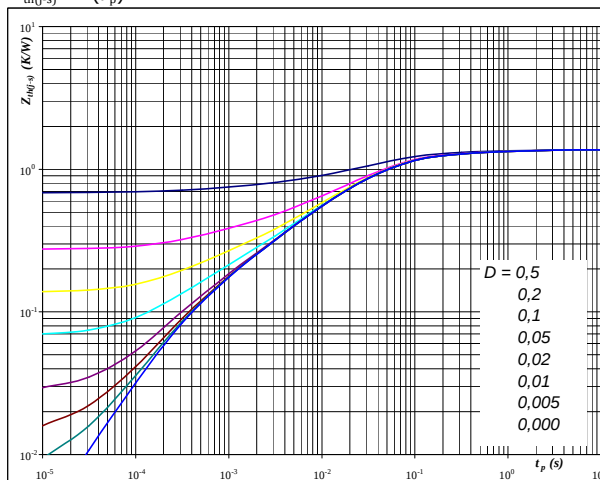
At

$$t_p = 250 \mu s$$

figure 2. Rectifier Diode

Diode transient thermal impedance
as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

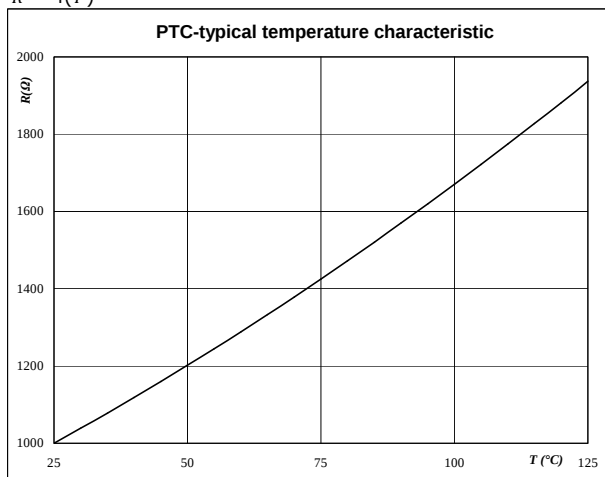
$$D = t_p / T$$
$$R_{th(j-s)} = 1,37 \text{ K/W}$$

Thermistor

figure 1. Thermistor

Typical PTC characteristic
as a function of temperature

$$R = f(T)$$





Switching Definitions Output Inverter

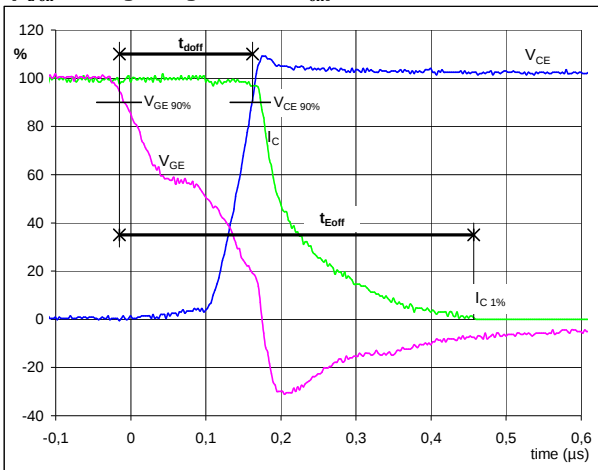
General conditions

T_j	=	125 °C
R_{gon}	=	16 Ω
R_{goff}	=	8 Ω

figure 1.

IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
(t_{Eoff} = integrating time for E_{off})

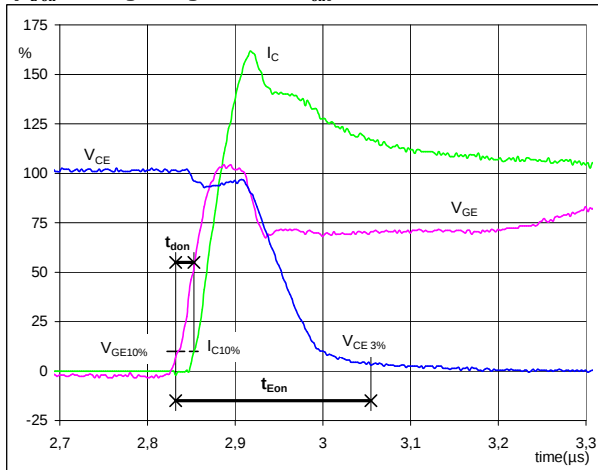


V_{GE} (0%) =	0	V
V_{GE} (100%) =	15	V
V_C (100%) =	300	V
I_C (100%) =	20	A
t_{doff} =	0,17	μ s
t_{Eoff} =	0,47	μ s

figure 2.

IGBT

Turn-on Switching Waveforms & definition of t_{donr} , t_{Eon}
(t_{Eon} = integrating time for E_{on})

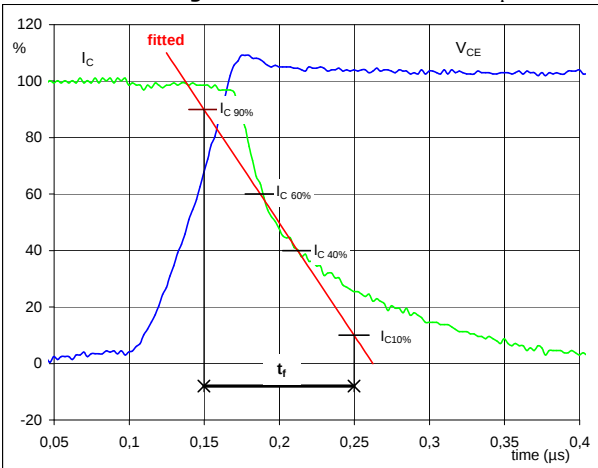


V_{GE} (0%) =	0	V
V_{GE} (100%) =	15	V
V_C (100%) =	300	V
I_C (100%) =	20	A
t_{don} =	0,02	μ s
t_{Eon} =	0,22	μ s

figure 3.

IGBT

Turn-off Switching Waveforms & definition of t_f

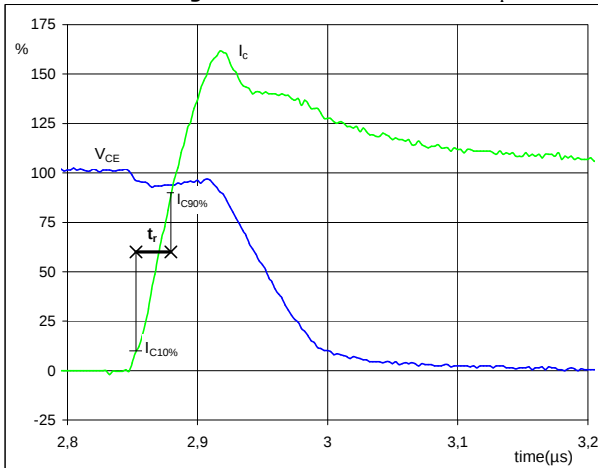


V_C (100%) =	300	V
I_C (100%) =	20	A
t_f =	0,10	μ s

figure 4.

IGBT

Turn-on Switching Waveforms & definition of t_r

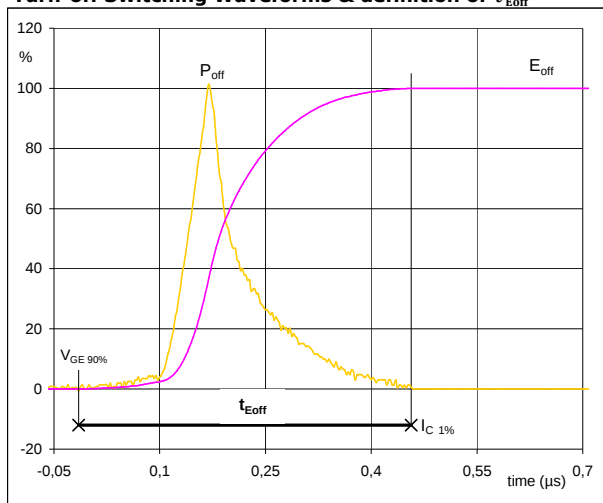


V_C (100%) =	300	V
I_C (100%) =	20	A
t_r =	0,03	μ s



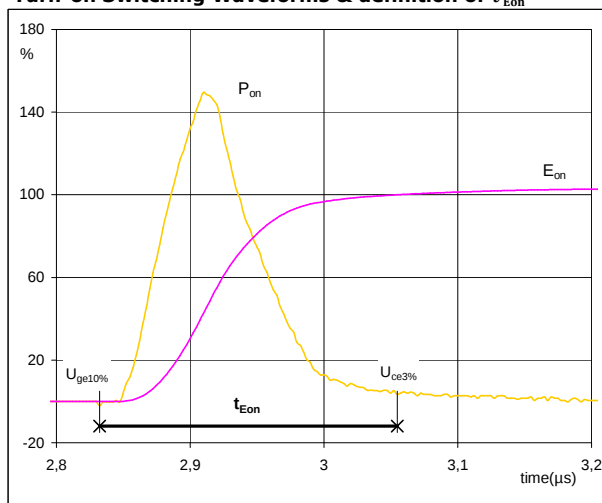
Switching Definitions Output Inverter

figure 5. IGBT

Turn-off Switching Waveforms & definition of t_{Eoff} 

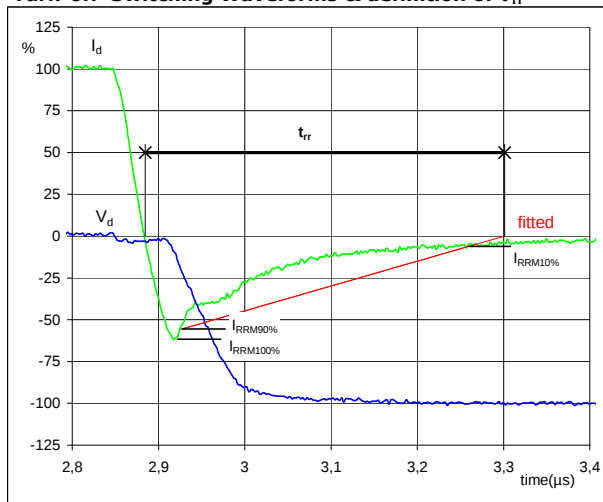
$P_{off} (100\%) = 5,98 \text{ kW}$
 $E_{off} (100\%) = 0,57 \text{ mJ}$
 $t_{Eoff} = 0,47 \text{ μs}$

figure 6. IGBT

Turn-on Switching Waveforms & definition of t_{Eon} 

$P_{on} (100\%) = 5,98 \text{ kW}$
 $E_{on} (100\%) = 0,71 \text{ mJ}$
 $t_{Eon} = 0,22 \text{ μs}$

figure 7. FWD

Turn-off Switching Waveforms & definition of t_{rr} 

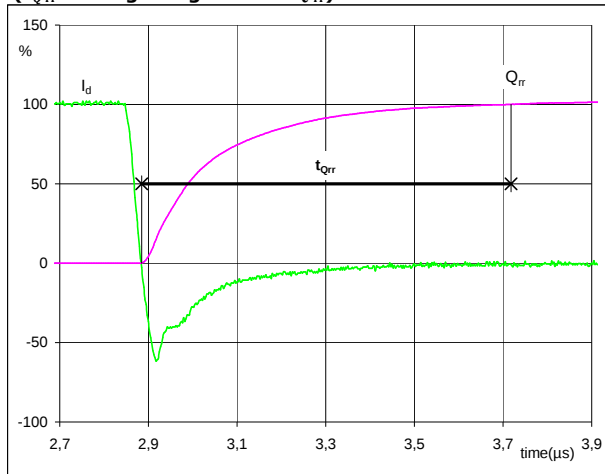
$V_d (100\%) = 300 \text{ V}$
 $I_d (100\%) = 20 \text{ A}$
 $I_{RRM} (100\%) = 12 \text{ A}$
 $t_{rr} = 0,35 \text{ μs}$



Switching Definitions Output Inverter

figure 8. FWD

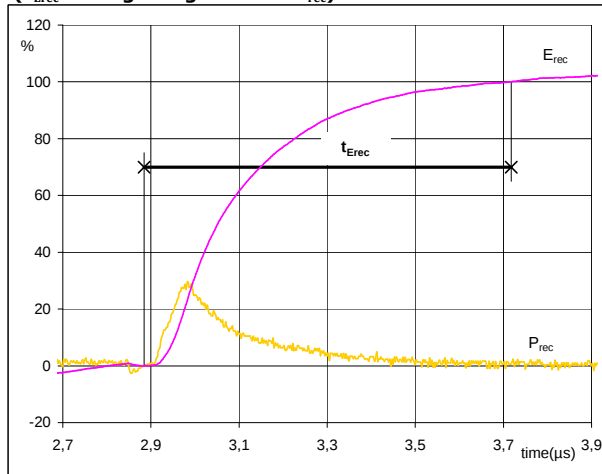
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) = 20 A
 Q_{rr} (100%) = 1,69 μC
 t_{Qrr} = 0,83 μs

figure 9. FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) = 5,98 kW
 E_{rec} (100%) = 0,33 mJ
 t_{Erec} = 0,83 μs



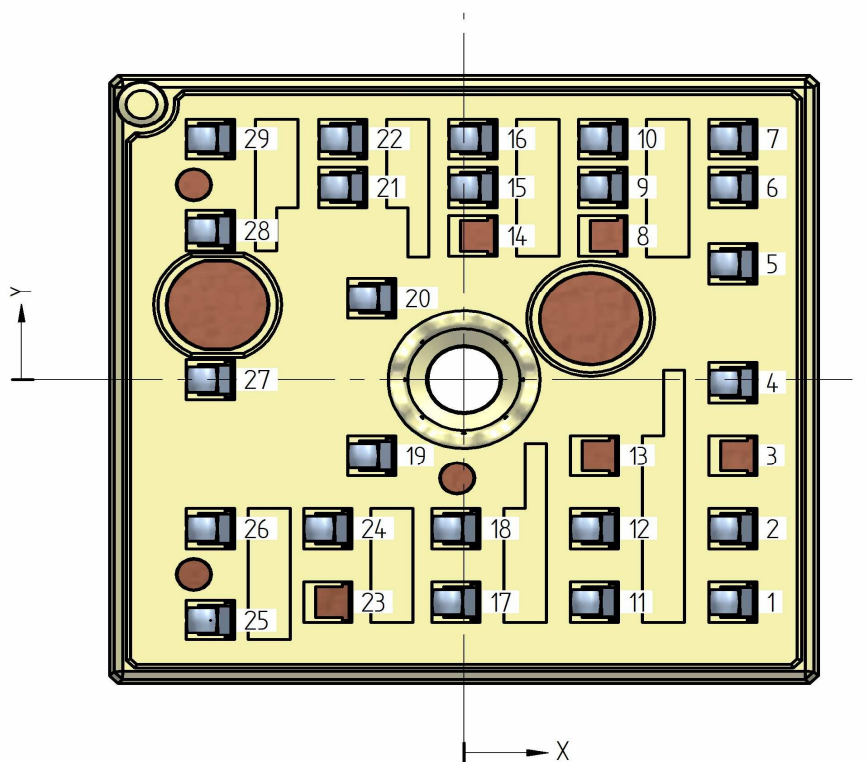
Ordering Code & Marking

Version	Ordering Code
With std lid (6.5mm height) + no thermal grease	V23990-K204-A-/0A/-PM
With thin lid (2.8mm height) + no thermal grease	V23990-K204-A-/0B/-PM
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	V23990-K204-A-/1A/-PM
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	V23990-K204-A-/1B/-PM
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	V23990-K204-A-/4A/-PM
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	V23990-K204-A-/4B/-PM
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	V23990-K204-A-/5A/-PM
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	V23990-K204-A-/5B/-PM

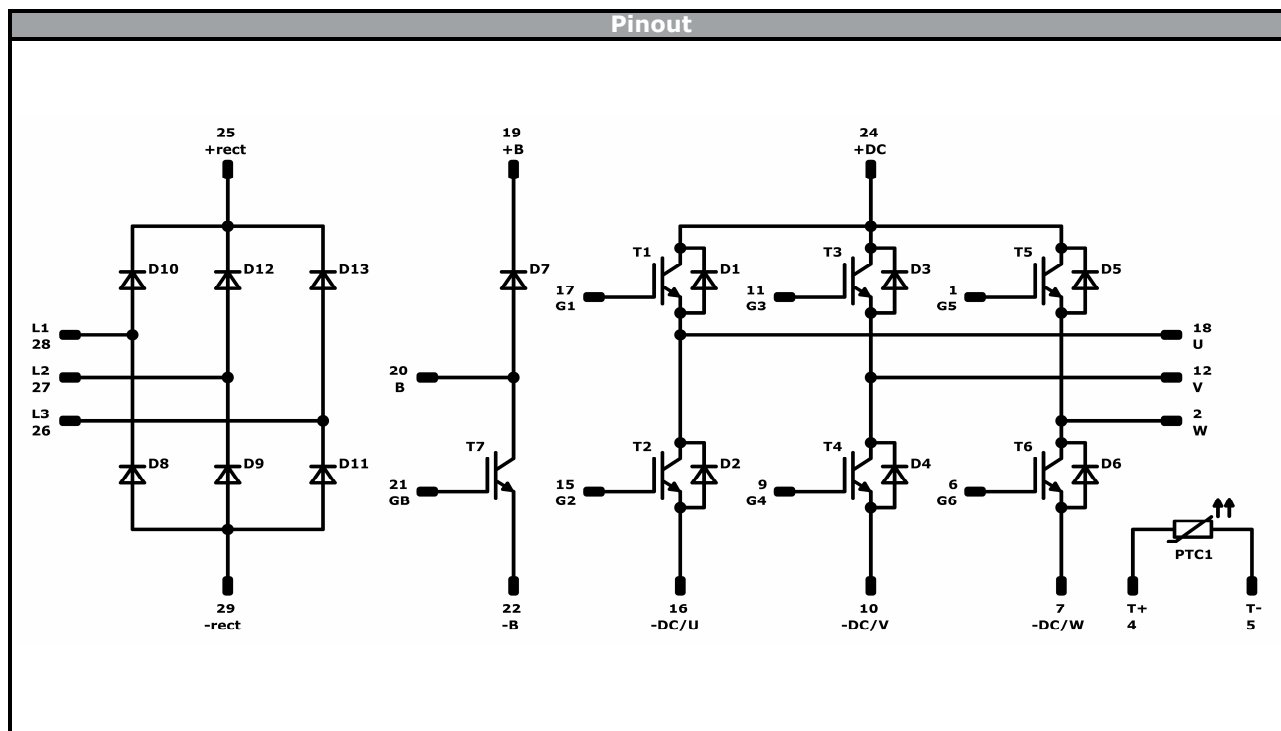
	Text	VIN	Date code	Name&Ver	UL	Lot	Serial
		VIN	WWYY	NNNNNVVV	UL	LLLL	SSSS
	Datamatrix	Type&Ver	Lot number	Serial	Date code		
		NNNNNVVV	LLLL	SSSS	WWYY		

Outline

Pad table [mm]			
Pad	X	Y	Function
1	15,93	-14,6	G5
2	15,93	-9,8	W
3	Not assembled		
4	15,93	-0,2	+T
5	15,93	7,62	-T
6	15,93	12,62	G6
7	15,93	15,8	-DC/W
8	Not assembled		
9	8,23	12,62	G4
10	8,23	15,8	-DC/V
11	7,73	-14,6	G3
12	7,73	-9,8	V
13	Not assembled		
14	Not assembled		
15	0,53	12,62	G2
16	0,53	15,8	-DC/U
17	-0,47	-14,6	G1
18	-0,47	-9,8	U
19	-5,47	-5	+B
20	-5,47	5,35	B
21	-7,17	12,62	GB
22	-7,17	15,8	-B
23	Not assembled		
24	-8,07	-9,8	+DC
25	-15,02	-15,8	+RECT
26	-15,02	-9,8	L3
27	-15,02	0	L2
28	-15,02	9,8	L1
29	-15,02	15,8	-RECT



Pad positions refers to center point. For more informations on pad design please see package data.



Identification					
ID	Component	Voltage	Current	Function	Comment
D8-D13	Rectifier	1600 V	25 A	Rectifier Diode	
T1-T6	IGBT	600 V	20 A	Inverter Switch	
D1-D6	FWD	600 V	20 A	Inverter Diode	
T7	IGBT	600 V	20 A	Brake Switch	
D7	FWD	600 V	20 A	Brake Diode	
PTC1	PTC			Thermistor	



Packaging instruction			
Standard packaging quantity (SPQ)	120	>SPQ Standard	<SPQ Sample

Handling instruction
Handling instructions for MiniSkiiP® 1 packages see vincotech.com website.

Package data
Package data for MiniSkiiP® 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-K204-A-D5-14	27 Sep. 2018	Thermal interface change to HPTP	1,2,3,8,10,14

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.